

Si-Mat

Silicon Materials

Your partner for SILICON WAFERS and
comprehensive Wafer Finishing Solutions
for over 20 years.
Industry - Science - Universities

BUYING SILICON WAFERS IS A MATTER OF CONFIDENCE

Silicon Wafers – 25.4 mm to 300 mm

- Prime, Monitor, Test, CZ, FZ
- SSP, DSP, As Cut, Lapped, Etched
- <100>, <111>, <110>
- Ultra Flat TTV < 1 μm
- Ultra Clean <50 @ 0.055 μm
- Precision of thickness 50 μm - 5,000 μm +/- 5 μm

SOI Wafers - 76.2 mm to 200 mm

- Silicon on Insulator, Fusion Bonding, CZ, FZ, SSP, DSP
- Device Layer: from 2 μm
- Buried Thermal Oxide: 0.2 μm - 2.4 μm
- Handle: thickness 300 μm - 2,000 μm

Customised Services

- Wafer Thinning, reduction of wafer size, Laser Marking
- Nano Grinding, Lapping, Polishing, Dicing
- Pocketwafer
- Reclaim

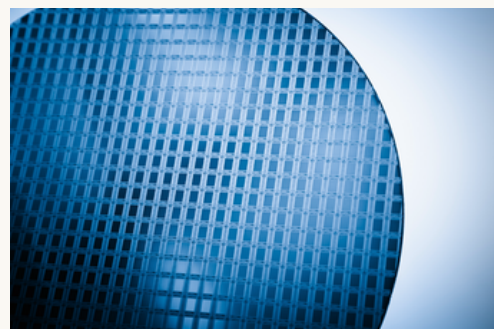
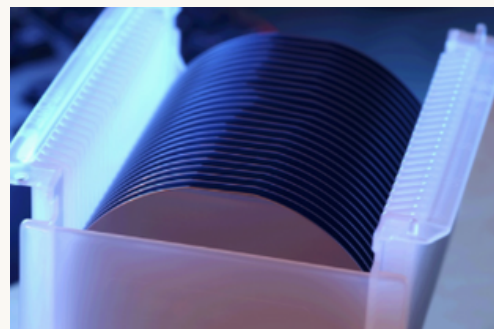
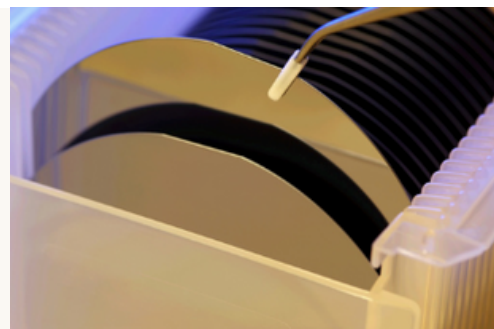
Coatings

- WET/ DRY Thermal Oxides, LPCVD/ PECVD Nitride, etc.

Glass Wafers

- Fused Quartz, Fused Silica, Borofloat

Sapphire Wafers, SOS, GaAs, Ge, InAs, Ingots



**Stay
Connected**

OFFICE

Si-Mat Silicon Materials
Viktor-Frankl-Straße 20
D-86916 Kaufering

CONTACT

Phone: +49 (0) 8191 - 478747
Email: info@si-mat.com
Website: www.si-mat.com